MAAP-010168

10 W Power Amplifier
0.5 - 3 GHz

Features
- Saturated Output Power: 41 dBm
- Linear Gain: 24 dB
- Power Added Efficiency: 30% at $P_{SAT}$
- 50 Ω Input / Output Match
- Ceramic Flange Mount Package
- RoHS* Compliant and 260°C Re-flow Compatible

Description
The MAAP-010168 is a two stage MMIC power amplifier designed for broadband high power applications. It can be used as either a driver or an output stage amplifier. This device is fully matched input and output to 50 Ω which eliminates any sensitive external RF tuning components.

The device is packaged in a lead free 10-lead flanged hermetic package for high volume manufacturing.

The MAAP-010168 is fabricated using a fully passivated high reliability pHEMT process. The device provides excellent power added efficiency and gain.

Ordering Information

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Package</th>
</tr>
</thead>
<tbody>
<tr>
<td>MAAP-010168-000000</td>
<td>Bulk</td>
</tr>
<tr>
<td>MAAP-010168-001SMB</td>
<td>Sample Board</td>
</tr>
</tbody>
</table>

1. Reference Application Note M567 for package handling and mounting procedure.

Functional Schematic

Pin Configuration

<table>
<thead>
<tr>
<th>Pin #</th>
<th>Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>$V_{GG2}$</td>
</tr>
<tr>
<td>2</td>
<td>$V_{GG1}$</td>
</tr>
<tr>
<td>3</td>
<td>RF Input$^3$</td>
</tr>
<tr>
<td>4</td>
<td>$V_{GG1}$</td>
</tr>
<tr>
<td>5</td>
<td>$V_{GG2}$</td>
</tr>
<tr>
<td>6</td>
<td>$V_{DD1}$</td>
</tr>
<tr>
<td>7</td>
<td>$V_{DD2}$</td>
</tr>
<tr>
<td>8</td>
<td>RF Output$^3$</td>
</tr>
<tr>
<td>9</td>
<td>$V_{DD2}$</td>
</tr>
<tr>
<td>10</td>
<td>$V_{DD1}$</td>
</tr>
</tbody>
</table>

2. Flange is DC and RF ground.
3. RF Input & RF Output ports have shunt DC paths to ground. No External DC voltage should be applied to the RF ports.

* Restrictions on Hazardous Substances, compliant to current RoHS EU directive.
Electrical Specifications:
Freq. = 0.5 - 3.0 GHz, \( V_{DD} = 10 \) V, \( I_{DQ} = 3.5 \) A, \( T_A = 25^\circ\text{C} \), \( Z_0 = 50 \) \( \Omega \)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Test Conditions</th>
<th>Units</th>
<th>Min.</th>
<th>Typ.</th>
<th>Max.</th>
</tr>
</thead>
<tbody>
<tr>
<td>Gain</td>
<td>Small signal</td>
<td>dB</td>
<td>19</td>
<td>24</td>
<td>—</td>
</tr>
<tr>
<td>Input Return Loss</td>
<td></td>
<td>dB</td>
<td>—</td>
<td>10</td>
<td>—</td>
</tr>
<tr>
<td>Output Return Loss</td>
<td></td>
<td>dB</td>
<td>—</td>
<td>10</td>
<td>—</td>
</tr>
<tr>
<td>P1dB</td>
<td></td>
<td>dBm</td>
<td>—</td>
<td>39</td>
<td>—</td>
</tr>
<tr>
<td>( P_{SAT} )</td>
<td></td>
<td>dBm</td>
<td>38</td>
<td>41</td>
<td>—</td>
</tr>
<tr>
<td>Current</td>
<td>( I_{DQ} )</td>
<td>A</td>
<td>—</td>
<td>3.5</td>
<td>5.5</td>
</tr>
<tr>
<td></td>
<td>( P_{SAT} )</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>PAE</td>
<td>( P_{SAT} )</td>
<td>%</td>
<td>—</td>
<td>30</td>
<td>—</td>
</tr>
<tr>
<td>Gate Bias</td>
<td></td>
<td>V</td>
<td>—</td>
<td>-0.7</td>
<td>—</td>
</tr>
<tr>
<td>Duty Cycle</td>
<td></td>
<td></td>
<td></td>
<td>—</td>
<td>100</td>
</tr>
</tbody>
</table>

Absolute Maximum Ratings\(^4,5\)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Absolute Maximum</th>
</tr>
</thead>
<tbody>
<tr>
<td>Input Power</td>
<td>24 dBm</td>
</tr>
<tr>
<td>Operating Supply Voltage</td>
<td>+11 V</td>
</tr>
<tr>
<td>Operating Gate Voltage</td>
<td>-2 V</td>
</tr>
<tr>
<td>Operating Temperature</td>
<td>-40°C to +85°C</td>
</tr>
<tr>
<td>Channel Temperature(^6,7)</td>
<td>+150°C</td>
</tr>
<tr>
<td>Storage Temperature</td>
<td>-65°C to +150°C</td>
</tr>
</tbody>
</table>

4. Exceeding any one or combination of these limits may cause permanent damage to this device.
5. MACOM does not recommend sustained operation near these survivability limits.
6. Operating at nominal conditions with \( T_J \leq +150\)°C will ensure \( MTTF > 1 \times 10^6 \) hours.
7. Junction Temperature \( (T_J) = T_C + \Theta_{JC} * ((V * I) - (P_{OUT} - P_{IN})) \)
   Typical thermal resistance \( (\Theta_{JC}) = 2.0^\circ\text{C/W} \)
   a) For \( T_C = 25^\circ\text{C} @ 1.5 \) GHz
   \( T_J = +80^\circ\text{C} @ +10 \) V, \( 4 \) A, \( P_{OUT} = 41 \) dBm, \( P_{IN} = 21 \) dBm
   b) For \( T_C = 85^\circ\text{C} @ 1.5 \) GHz
   \( T_J = +138^\circ\text{C} @ +10 \) V, \( 3.9 \) A, \( P_{OUT} = 41 \) dBm, \( P_{IN} = 21 \) dBm

Operating the MAAP-010168
The MAAP-010168 is static sensitive. Please handle with care. To operate the device, follow these steps. Ramp down or shutdown in reverse order (gate bias on first and off last). All \( V_{GG} \) pins should have the same voltage applied at all times.
1. Apply \( V_{GG} (-1.5 \) V).
2. Apply \( V_{DD} (10.0 \) V Typical).
3. Set \( I_{DQ} \) by adjusting \( V_{GG} \).
4. Apply \( RF_{IN} \).

Handling Procedures
Please observe the following precautions to avoid damage:

Static Sensitivity
Gallium Arsenide Integrated Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.
Recommended Bias Configuration

C_x = 1000 \mu F  
C_y = 1 \mu F  
C_z = 10 \mu F

Sample Board Layout
MAAP-010168 Recommended Layout

Below is the recommended layout for the MAAP-010168. For optimal stability MACOM recommends adding bias decoupling capacitors of 10 μF at the entry point of $V_G$ and $V_{DD}$ (At the DC connections Header PIN). It is also recommended to add shunt decoupling capacitors of 1 μF & 1000 pF at the gate and drain pins of MAAP-010168 as shown in the details A below.

MACOM can provide gerber files of the sample board layout upon request.

MAAP-010168 Sample Board Layout

![Sample Board Layout Diagram]

Parts List

<table>
<thead>
<tr>
<th>Item #</th>
<th>Component / Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>10</td>
<td>Test Board, RO4350, ½ Oz copper, 10 mil thick</td>
</tr>
<tr>
<td>20</td>
<td>SMA Edge Mount Connectors</td>
</tr>
<tr>
<td>30</td>
<td>2x15 Right Angle Connector, 0.1 Grid</td>
</tr>
<tr>
<td>40</td>
<td>Capacitor, 10 μF, 10%, 16 V, 1210, X5R</td>
</tr>
<tr>
<td>50</td>
<td>Capacitor, 1 μF, 10%, 16 V, 0402, X5R</td>
</tr>
<tr>
<td>60</td>
<td>Capacitor, 1000 pF, 10 %, 25 V, 0402, X5R</td>
</tr>
</tbody>
</table>
Typical Performance Curves

**Gain**

- S21 (dB)

**Input Return Loss**

- S11 (dB)

**Output Return Loss**

- S22 (dB)

**Reverse Isolation**

- S12 (dB)

**Output Power (dBm)**

- +25°C
- -40°C
- +85°C

**Output Power (W)**

- +25°C
- -40°C
- +85°C
Typical Performance Curves

**Power Gain**

- Frequency (GHz)
- Power Gain (dBm)
- Temperature: +25°C, -40°C, +85°C

**Power Added Efficiency (PAE)**

- Frequency (GHz)
- PAE (%)
- Temperature: +25°C, -40°C, +85°C

**Drain Current**

- Frequency (GHz)
- Drain Current (A)
- Temperature: +25°C, -40°C, +85°C

**Output Power Sweep**

**@ 0.7 GHz**

- Input Power (dBm)
- Output Power (dBm)
- Temperature: +25°C, -40°C, +85°C

**@ 1.5 GHz**

- Input Power (dBm)
- Output Power (dBm)
- Temperature: +25°C, -40°C, +85°C

**@ 2.5 GHz**

- Input Power (dBm)
- Output Power (dBm)
- Temperature: +25°C, -40°C, +85°C
Typical Performance Curves

**Power Gain vs. Input Power @ 0.7 GHz**

![Power Gain vs. Input Power @ 0.7 GHz](image1)

**Power Gain vs. Output Power @ 0.7 GHz**

![Power Gain vs. Output Power @ 0.7 GHz](image2)

**Power Gain vs. Input Power @ 1.5 GHz**

![Power Gain vs. Input Power @ 1.5 GHz](image3)

**Power Gain vs. Output Power @ 1.5 GHz**

![Power Gain vs. Output Power @ 1.5 GHz](image4)

**Power Gain vs. Input Power @ 2.5 GHz**

![Power Gain vs. Input Power @ 2.5 GHz](image5)

**Power Gain vs. Output Power @ 2.5 GHz**

![Power Gain vs. Output Power @ 2.5 GHz](image6)
8. Power dissipation should not exceed the maximum plot shown above to maintain $T_J < 150°C$. It is recommended to monitor power dissipation and decrease power dissipation in the device as required.

Ceramic Flange Mount Package†

† Reference Application Note M538 for lead-free solder reflow recommendations.

This is a high frequency, low thermal resistance package. The package consists of a cofired ceramic construction with a copper-tungsten base and iron-nickel-cobalt leads. The finish consists of electrolytic gold over nickel plate.
MACOM Technology Solutions Inc. All rights reserved.

Information in this document is provided in connection with MACOM Technology Solutions Inc ("MACOM") products. These materials are provided by MACOM as a service to its customers and may be used for informational purposes only. Except as provided in MACOM's Terms and Conditions of Sale for such products or in any separate agreement related to this document, MACOM assumes no liability whatsoever. MACOM assumes no responsibility for errors or omissions in these materials. MACOM may make changes to specifications and product descriptions at any time, without notice. MACOM makes no commitment to update the information and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to its specifications and product descriptions. No license, express or implied, by estoppels or otherwise, to any intellectual property rights is granted by this document.

THESE MATERIALS ARE PROVIDED "AS IS" WITHOUT WARRANTY OF ANY KIND, EITHER EXPRESS OR IMPLIED, RELATING TO SALE AND/OR USE OF MACOM PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, CONSEQUENTIAL OR INCIDENTAL DAMAGES, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT. MACOM FURTHER DOES NOT WARRANT THE ACCURACY OR COMPLETENESS OF THE INFORMATION, TEXT, GRAPHICS OR OTHER ITEMS CONTAINED WITHIN THESE MATERIALS. MACOM SHALL NOT BE LIABLE FOR ANY SPECIAL, INDIRECT, INCIDENTAL, OR CONSEQUENTIAL DAMAGES, INCLUDING WITHOUT LIMITATION, LOST REVENUES OR LOST PROFITS, WHICH MAY RESULT FROM THE USE OF THESE MATERIALS.

MACOM products are not intended for use in medical, lifesaving or life sustaining applications. MACOM customers using or selling MACOM products for use in such applications do so at their own risk and agree to fully indemnify MACOM for any damages resulting from such improper use or sale.